

- Member of the Texas Instruments *Widebus*™ Family
- State-of-the-Art *EPIC-II B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Packaged in Plastic 300-mil Shrink Small-Outline (SSOP) Packages

description

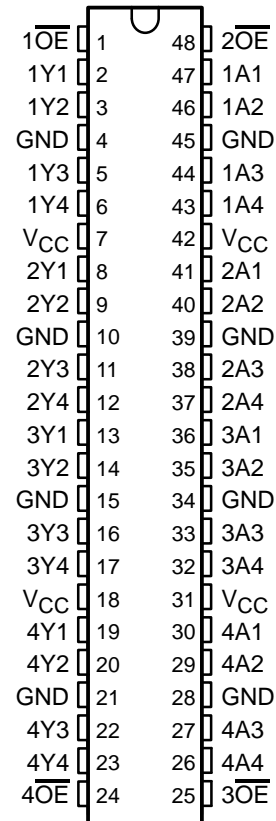
The SN74ABT16240 is a 16-bit buffer and line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. This device provides inverting outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16240 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ABT16240 is characterized for operation from -40°C to 85°C .

DL PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	L
L	L	H
H	X	Z

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SN74ABT16240

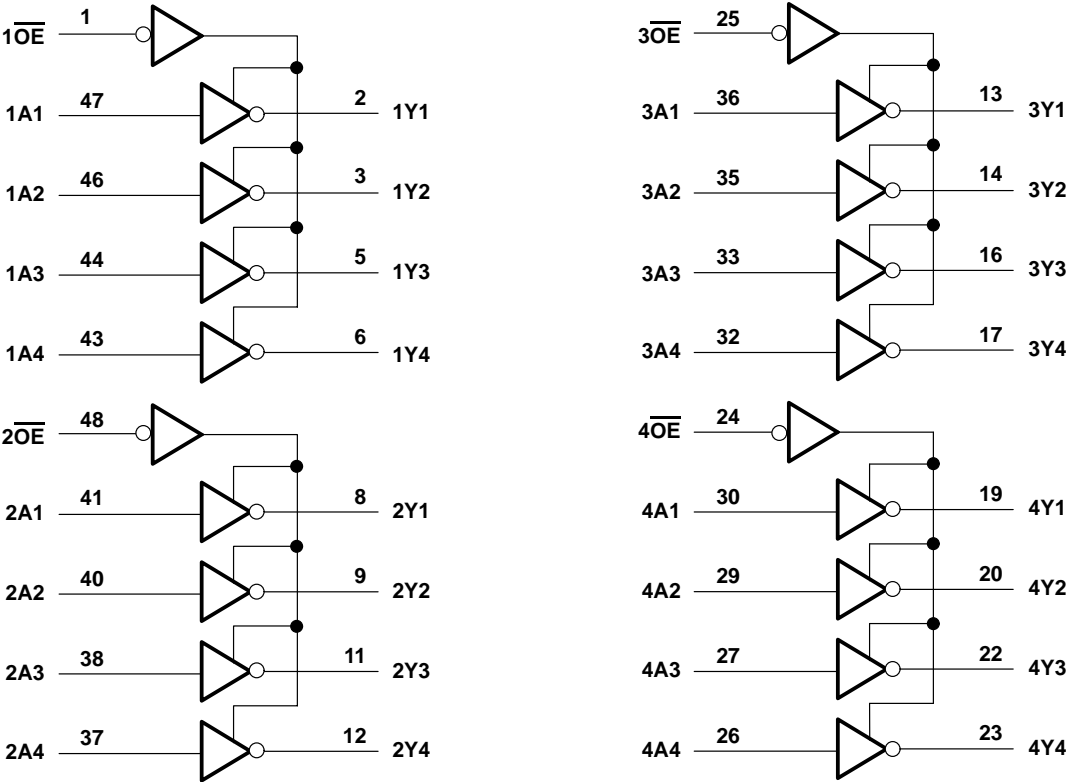
16-BIT BUFFER/DRIVER

WITH 3-STATE OUTPUTS

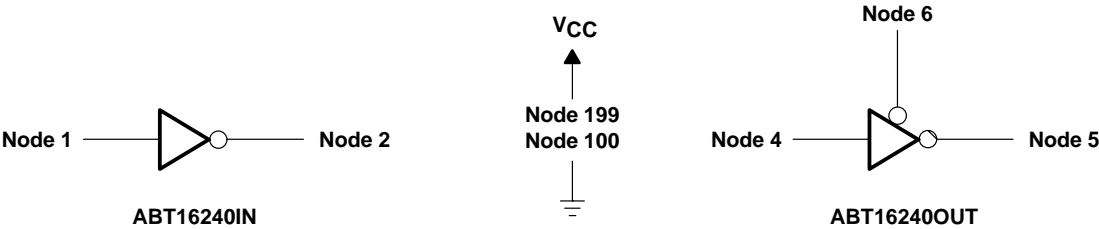
SCBS346 – MAY 1994

SPICE I/O MODEL

logic diagram (positive logic)



SPICE block diagram



SPICE FUNCTION TABLE

NODE		OPERATION	NODE			OPERATION
1	2		4	5	6	
L	H	Input	L	H	L	Output
H	L	Input	H	L	L	Output
			X	Z	H	Hi-Z

SPICE netlist

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*      ABT16240 SPICE I/O MODEL SUBCIRCUIT
*      ADVANCED BUS INTERFACE
*      ADVANCED SYSTEM LOGIC, TEXAS INSTRUMENTS
*
*      SUBCIRCUITS:  ABT16240IN, ABT16240OUT
*
*      PACKAGE PARASITICS
*          .LIB 'PKGS.LIB'      SSOP48
*
*      PROCESS MODELS
*          .LIB 'EPIC2B.LIB'  NOMINAL_L13
*          .LIB 'EPIC2B.LIB'  STRONG_L13
*          .LIB 'EPIC2B.LIB'  WEAK_L13
*
*      ABT16240 INPUT SUBCIRCUIT
*      NODES:          INPUT NODE
*                      |
*                      | INTERNAL OUTPUT NODE
*                      | VCC
*                      | GND
*
*
*      .SUBCKT ABT16240IN      1      2      199      100
*      X_PKGIN      1      1001
*      X_PKGVCC      199      1199
*      X_PKG_GND      100      1100
*      XABT16240IN      1001      2      1199      1100
*      .ENDS ABT16240IN
*
*      ABT16240 OUTPUT SUBCIRCUIT
*      NODES:          INTERNAL INPUT NODE
*                      |
*                      | OUTPUT NODE
*                      | INTERNAL OE NODE
*                      | VCC
*                      | GND
*
*
*      .SUBCKT ABT16240OUT      4      5      6      199      100
*      X_PKGOUT      5      1005
*      X_PKGVCC      199      1199
*      X_PKG_GND      100      1100
*      XABT16240OUT      4      1005      6      1199      1100
*      .ENDS ABT16240OUT
*
*      .SUBCKT ABT16240__IN      501      502      599      500
*      XP1      502      504      506      599      PM      WP=200U      LP=0.8U
*      XP2      509      502      599      599      PM      WP=20U      LP=0.8U
*      XP3      506      509      599      599      PM      WP=85U      LP=0.8U
*      XP4      508      500      599      599      PM      WP=50U      LP=0.8U
*      XN1      502      504      500      500      NM      WN=220U      LN=0.8U
*      XN2      509      502      500      500      NM      WN=20U      LN=0.8U
*      XN4      599      500      508      500      NM      WN=20U      LN=0.8U
*      QA      599      508      507      Q2_NPN      10
*      QB      599      507      506      Q5_NPN      60
*      Q_ESD1      501      500      500      Q7_NPN      200
*      Q_ESD      504      505      500      Q5_NPN      46
*      XR1      506      507      507      507      RMOS      WR=4U      RES=6K
*      RESD1      501      504      50
*      RESD2      505      500      1K
*      CBP      501      500      0.3P
*      CL      502      500      0.2P
*      .ENDS ABT16240__IN
*
*      .SUBCKT ABT16240__OUT      601      602      603      699      600
*      XP1      605      603      699      699      PM      WP=200U      LP=0.8U
*      XP4      601      603      621      699      PM      WP=40U      LP=0.8U
*      XP5      613      601      605      699      PM      WP=30U      LP=0.8U
*      XP10      618      603      699      699      PM      WP=50U      LP=0.8U
*      XP11      607      612      605      699      PM      WP=60U      LP=0.8U
*      XN1      607      601      608      600      NM      WN=100U      LN=0.8U

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